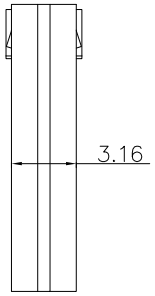
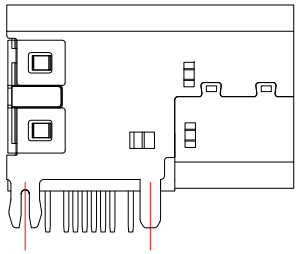
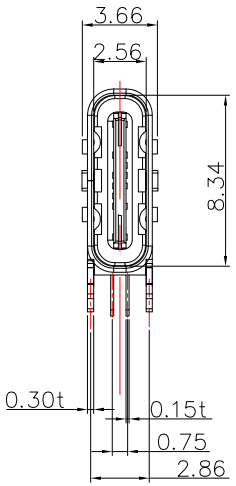
SBC-140P-20x-S242

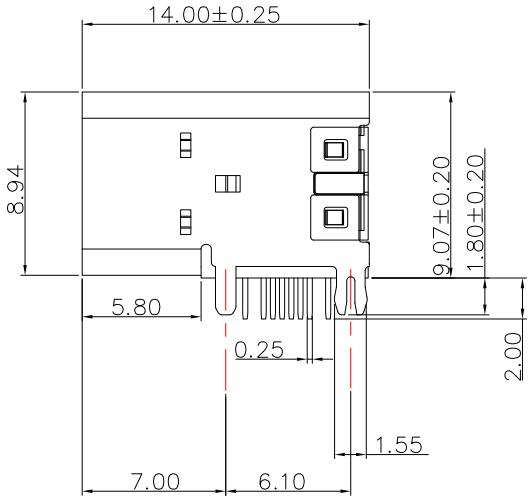
鍍層厚度：

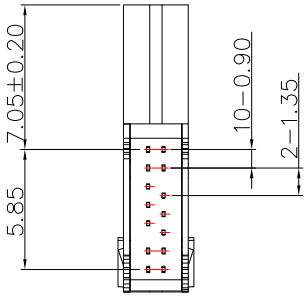
Blank : 1u"
2 : 15u"
3 : 30u"

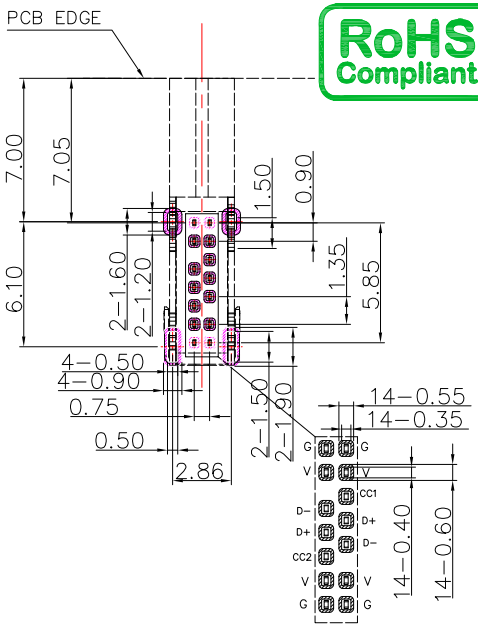












RECOMMENDED P.C.B. LAYOUT

SPECIFICATIONS

Electrical:

1.Dielectric Withstand Voltage: 100V AC

2.Contact Resistance: 40 mΩ Max

3.Insulation Resistance: 100 MΩ Min

Mechanical:

1.Connector Mate and Unmate Force

1.1 Mate force: 5~20 N

1.2 Unmate force: 8~20 N

Material:

1.Housing: High-Temp

2.Contact: Copper Alloy

3.Shell: SUS

Finish:

1.Contact: Plated Gold in Mating Area ;
Tin Plated on Solder Balls ;
Nickel under plated overall

2.Shell: Nickel under Plated surface layer

ITEM NO.	DESCRIPTION	DRAWN	DATE
1	新增PCB LAYOUT尺寸	Jack	090619

CONTACT 建倚科技股份有限公司
CONTACT TECHNOLOGY CORP.

TOLERANCE UNLESS OTHERWISE STATED :
Up to 5 ±0.2
Above 5 ~ 15 ±0.3
Above 15 ~ 30 ±0.4
Above 30 ~ 50 ±0.5
Angle ±0.3°

3RD. ANGEL'S | UNITS MM

DRAWN BY: Jack Lu	DATE 09/06/19	MAT'L	
CHECKED BY: Jacky Chen	DATE 09/06/19	FINISH	
APPROVED BY: Tony Kao	DATE 09/06/19	SCALE 1 : 1	SHEET NO. 1 of 1

TITLE	CONNECTOR		
MODLE	USB 3.1 側插母座 14 PIN		
DWG NO.	SBC-140P-20x-S242	SIZE	A4
PART NO.	SBC-140P-20x-S242	VER	R1